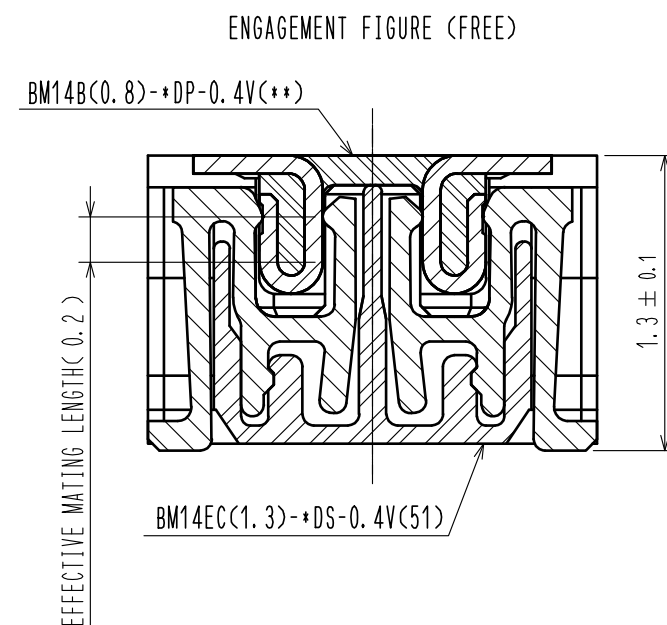
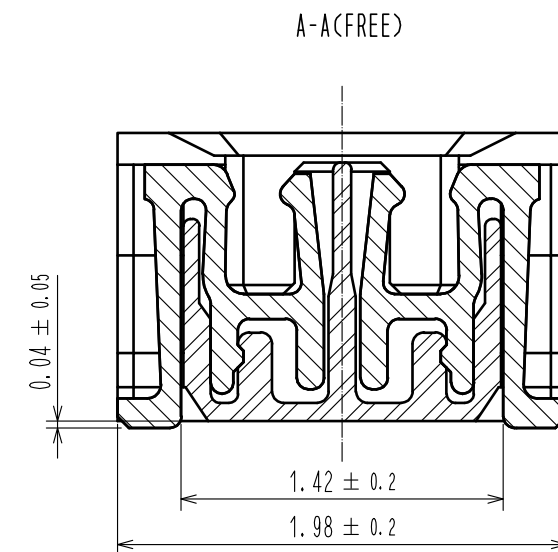
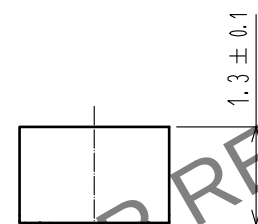
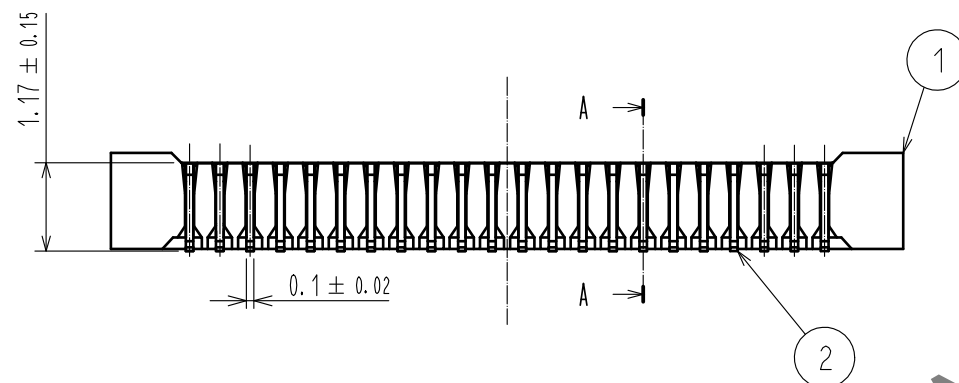
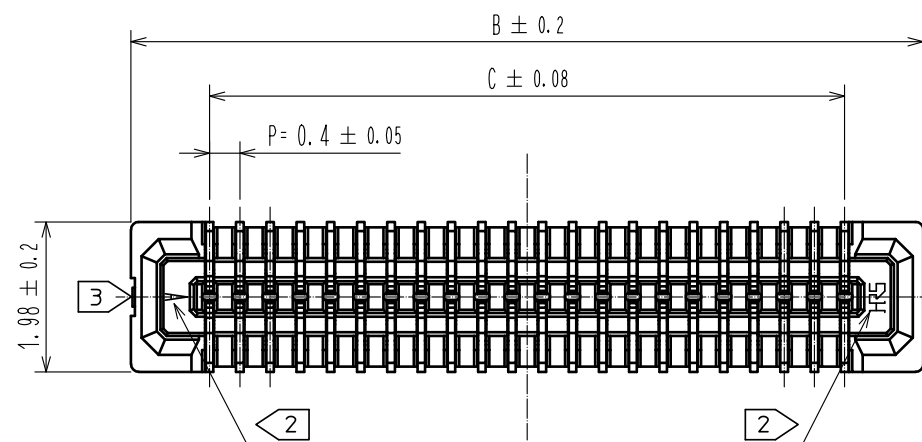
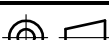


May.1.2024 Copyright 2024 HIROSE ELECTRIC CO., LTD. All Rights Reserved.
In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.



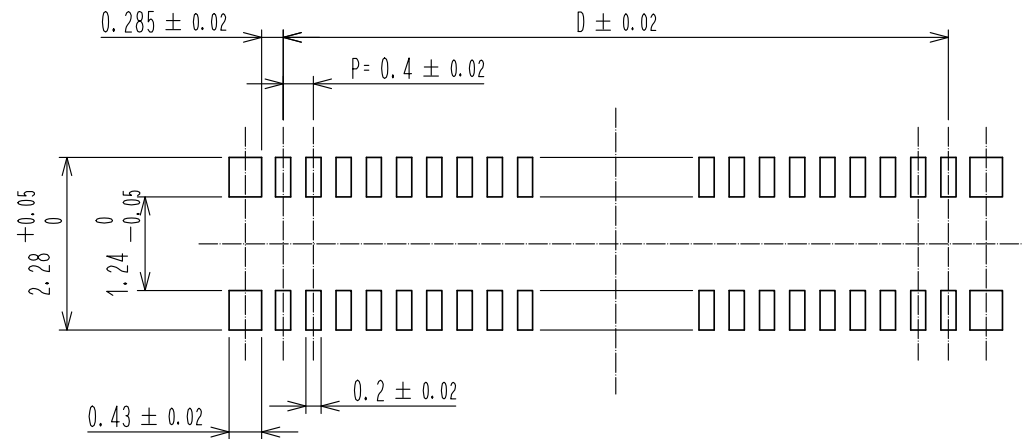
NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
3. GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.

PART No.	CODE No.	B	C
BM14EC(1.3)-14DS-0.4V(51)	-	4.48	2.4
BM14EC(1.3)-16DS-0.4V(51)	CL684-8180-0-51	4.88	2.8
BM14EC(1.3)-24DS-0.4V(51)	-	6.48	4.4
BM14EC(1.3)-28DS-0.4V(51)	-	7.28	5.2
BM14EC(1.3)-34DS-0.4V(51)	-	8.48	6.4
BM14EC(1.3)-44DS-0.4V(51)	CL684-8155-3-51	10.48	8.4
BM14EC(1.3)-54DS-0.4V(51)	CL684-8157-9-51	12.48	10.4
BM14EC(1.3)-64DS-0.4V(51)	-	14.48	12.4

2	PHOSPHOR BRONZE	CONTACT AREA : GOLD 0.05 μm MIN.	6	PS	CLEAR (REINFORCEMENT COLLAR)			
		SMT LEAD : GOLD 0.05 μm MIN.	5	PS	BLACK (PLASTIC REEL)			
		UNDERPLATING : NICKEL 1 μm MIN.	4	POLYESTER	CLEAR (COVER TAPE)			
1	LCP	UL94 V-0, BLACK	3	PS	CLEAR (EMBOSSED CARRIER TAPE)			
NO.	MATERIAL	FINISH . REMARKS		NO.	MATERIAL	FINISH . REMARKS		
UNITS mm		SCALE 10 : 1	 COUNT 3	DESCRIPTION OF REVISIONS DIS-H-00002669		DESIGNED NY. YAMASHIRO	CHECKED TS. MIYAZAKI	DATE 17. 03. 07
 HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA	10. 04. 23	DRAWING NO. EDC3-327823-01				
		CHECKED : TS. MIYAZAKI	10. 04. 23	PART NO. BM14EC(1.3)-*DS-0.4V(51)				
		DESIGNED : TR. YUNOKI	10. 04. 23	CODE NO. CL684				
		DRAWN : YN. SAKAMOTO	10. 04. 22	 				

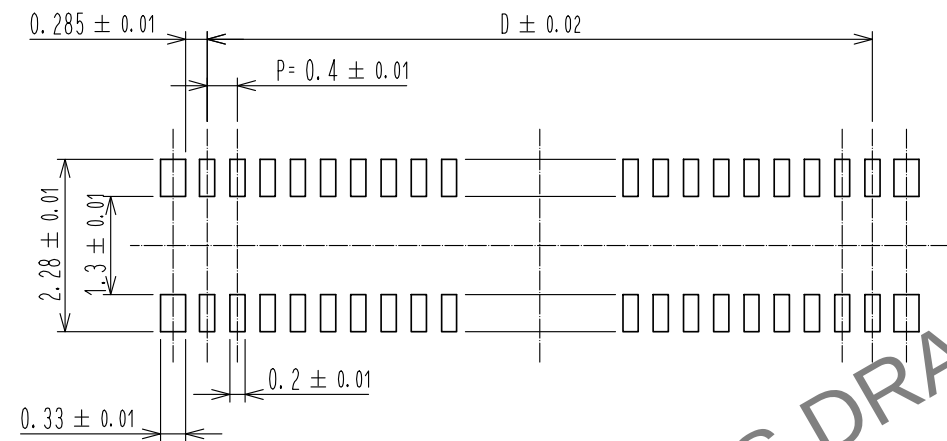
May.1.2024 Copyright 2024 HIROSE ELECTRIC CO., LTD. All Rights Reserved.
In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

◆ RECOMMENDED PCB LAYOUT



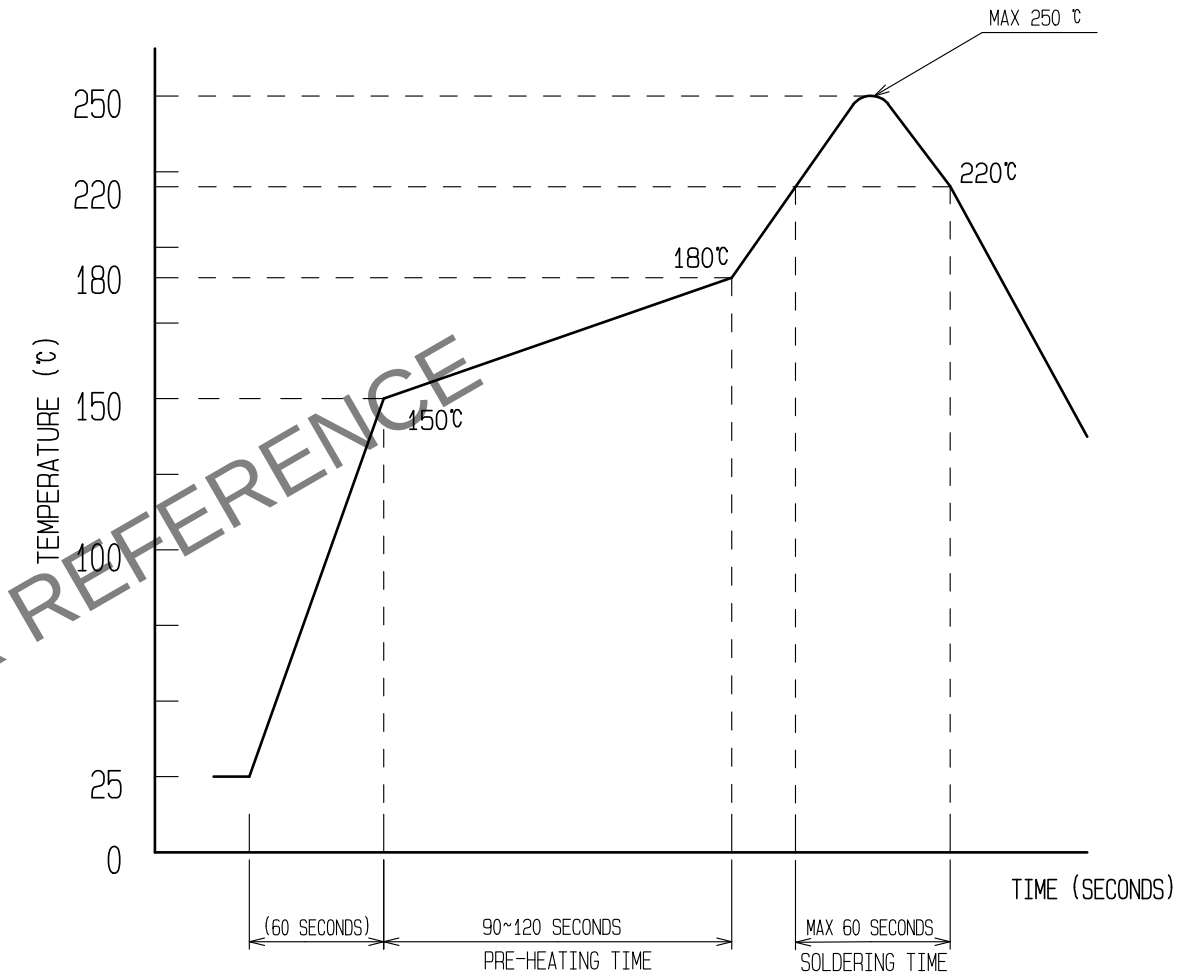
◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



PART No.	D
BM14EC(1.3)-14DS-0.4V(51)	1.6
BM14EC(1.3)-16DS-0.4V(51)	2.0
BM14EC(1.3)-24DS-0.4V(51)	3.6
BM14EC(1.3)-28DS-0.4V(51)	4.4
BM14EC(1.3)-34DS-0.4V(51)	5.6
BM14EC(1.3)-44DS-0.4V(51)	7.6
BM14EC(1.3)-54DS-0.4V(51)	9.6
BM14EC(1.3)-64DS-0.4V(51)	11.6

4> RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220°C, 60 SEC. MAX.

(PEAK TEMPERATURE: 250°C MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN): 150°C

PRE-HEAT TEMPERATURE(MAX): 180°C

PRE-HEAT TIME: 90-120 sec.



THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-327823-01
PART NO.	BM14EC(1.3)-*DS-0.4V(51)
CODE NO.	CL684

2/3

